Official Conference Assistant

Kinki Nippon Tourist Co., Ltd. has been appointed as the official conference assistant.

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Further Information

For further information, please visit ICSCRM 2026 official web site at:

https://icscrm2026.org/

Or contact general affairs of the executive committee:

e-mail: secretariat@icscrm2026.org

International Conference on Silicon Carbide and Related Materials 2026

ICSCRM
YOKOHAMA, JAPAN 2026

Final Announcement and Call for Papers

ICSCRM
YOKOHAMA, JAPAN 2026

International Conference on Silicon Carbide and Related Materials 2026

September 27(Sun.) - October 2 (Fri.), 2026
Yokohama, Japan

Venue: PACIFICO YOKOHAMA North
https://icscrm2026.org

Abstract Deadline: May 11, 2026

Endorsed by The Japan Society of Applied Physics
Supported by City of Yokohama

Scope

The aim of this conference is to discuss recent advances in crystal growth, characterization, material property control, device fabrication and packaging technologies, system applications, and quantum technologies related to silicon carbide (SiC) and related materials.

In addition, the conference will highlight the latest research results in device design, fabrication, characterization, packaging, and system applications aimed at improving device performance and reliability, and contributing to the realization of cutting-edge devices and systems for green innovation.

The conference also serves as an international forum for the exchange of ideas on recent scientific and technical issues among researchers and engineers from industry, academia, and public sectors.

The scope of this conference covers a wide range of topics on silicon carbide and related materials, including other wide bandgap (WBG) semiconductors such as III-nitrides, oxides, and diamond.

Topics

- Material and Growth

Bulk and epitaxial growth, Wafer manufacturing

- Defects and Characterization

Fundamental properties, Point and extended defects, Characterization and imaging techniques, Surface characterization and modification

- Device Process and Characterization

MOS interface and insulators, Device fabrication processes (e.g. Implantation, Oxidation, Surface treatments, Metallization, Ohmic and Schottky contact formations, and Dry etching technologies)

- Device Physics, Design, and Characterization

Device design and testing, Novel device concepts and Characterization, Modelling and Simulation, Novel measurements techniques

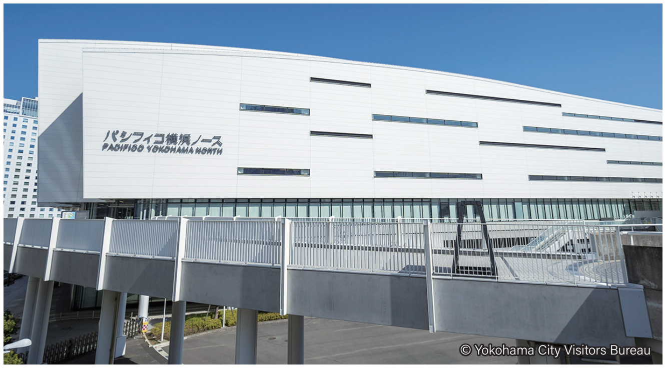
- Devices and Module Reliability, Packaging, and Applications

Modular and driver-circuit technologies, System applications, Packaging and device reliabilities

- Quantum Applications and Sensors

Theoretical and experimental studies, Optical and electrical quantum techniques, for Magnetic, Electric field, and Temperature sensors, Single-photon sources and detectors for SiC and related materials including other wide bandgap semiconductors such as III-nitrides, oxides, and diamond.

Venue



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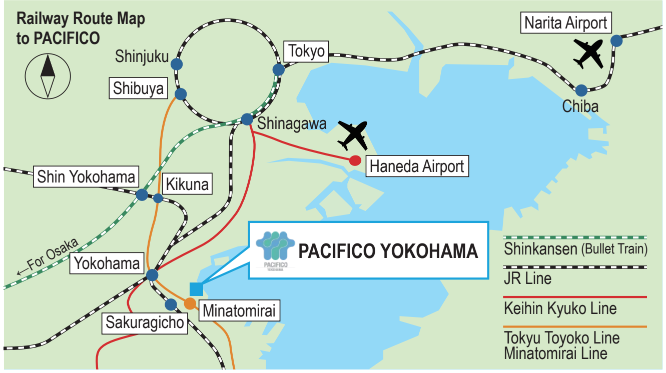
Venue PACIFICO YOKOHAMA North

PACIFICO Yokohama North, which is located in the waterfront area of the Minato Mirai 21 district, a new town in Yokohama, is one of the largest convention complexes in the world. Opened in 2020, PACIFICO YOKOHAMA North features the largest multi-purpose hall in Japan.



Important Dates

Deadline for regular abstract submission		**11 May, 2026**
Acceptance notification of regular paper		**6 July, 2026**
Deadline for late news abstract submission		**17 August, 2026**
Acceptance notification of late news paper		**31 August, 2026**
Deadline for sponsorship application	▶ **First stage**	**31 May, 2026**
	▶ **Final stage**	**16 August, 2026**
Deadline for exhibition application		**31 May, 2026**
Deadline for registration	▶ **Early bird**	**17 July, 2026**
	▶ **Standard**	**7 September, 2026**
Deadline for proceedings submission		**22 September, 2026**

Overview of Schedule (tentative)

	27 Sep.	28 Sep.	29 Sep.	30 Sep.	1 Oct.	2 Oct.
8:30			Oral 8:40-12:30	Oral 8:40-12:30	Plenary 8:40-9:25	Oral 8:40-12:30
9:00		Opening & Plenary 9:00-11:00				
9:30						
10:00	Tutorial				Oral 9:50-12:00	
10:30						
11:00		Lunch 11:10-12:55				
11:30						
12:00					Lunch 12:00-13:30	
12:30			Lunch 12:30-14:00	Lunch 12:30-14:00		Lunch 12:30-14:00
13:00		Oral 12:55-16:20				
13:30					Oral 13:30-14:50	
14:00			Oral 14:00-15:50	Oral 14:00-15:50		Oral 14:00-15:30
14:30						
15:00					Poster 15:00-17:00	
15:30						Plenary 15:30-16:15
16:00			Poster 16:00-18:00	Poster 16:00-18:00		
16:30		Poster 16:30-18:30				Closing 16:15-16:45
17:00						
17:30						
18:00	Welcome Reception 18:00-20:00				Bauquet 18:00-21:30	
18:30		Industrial Session 18:40-20:40				
19:00						
19:30						
20:00						
20:30						
21:00						
21:30						

Industrial Session

Commercially available technologies for materials, devices and fabrication/characterization equipment, as well as recent market research and other industrial information will be presented in the Industrial Session on Monday evening, September 28.

Invited Speakers

Plenary lectures

Yoshifumi Kato (MIRISE Technologies Corporation)

Michael Krieger (Friedrich-Alexander-Universität Erlangen-Nürnberg)

Rajib Datta (GE Vernova Advanced Research Center)

Yasunori Tanaka (National Institute of Industrial Science and Technology)

Invited Speakers

Invited Speakers list will be updated on the ICSCRM2026 web site.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Notes to Authors and Participants

The official language of the conference is English, which will be used for all presentations and printed materials. Authors are expected to present their papers in person at the conference. If authors cannot attend or wish to withdraw their paper, the technical program chair must be notified well in advance at the following e-mail address: secretariat@icscrm2026.org.

It should be noted that photo, audio and video recordings are prohibited during the oral/poster session in the conference.

Submission of Abstracts

Abstracts should be submitted to ICSCRM 2026 via the online submission system. All abstracts must be written in English and should not exceed two pages, including figures, tables, captions, and references. The abstract should include the title, author name(s), affiliation(s), and contact information.

Submitted abstracts will be reviewed by the Technical Program Committee, and accepted abstracts will be included in the conference program and distributed to conference participants.

Abstract submission deadline: **May 11, 2026** **(JST, UTC+9)**

For detailed instructions on abstract format and submission procedures, please refer to the submission page on the conference website.

Late News Papers

Late news abstracts will be accepted for a limited number of oral or poster presentations. Selection will be more competitive than for regular abstracts, and submissions should report new results that were not available before May 11, 2026. The submission period for late news abstracts will be open from July 13 to August 17, 2026. The submission period for late news abstracts will be open from July 17 to August 17, 2026 (JST=UTC+9).

Proceedings

The manuscript submission deadline for the ICSCRM 2026 Technical Proceedings is September 22, 2026.

An email containing instructions for manuscript submission will be sent to the corresponding authors of all accepted abstracts. Manuscripts will be published in the Proceedings of Silicon Carbide and Related Materials 2026 by Trans Tech Publications. Each manuscript must be based on the submitted abstract and the corresponding conference presentation. All manuscripts will undergo blind peer review and can be edited through the online Trans Tech (scientific.net) system.


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Registration

Fees and Registration

All participants except plenary and invited speakers need to register for the conference through the "Confit", a dedicated registration system or on-site registration desk. The registration fees are as follows:

	Until July 17 (JST)	July 18 – September 7 (JST)	On-site
Regular	JPY 110,000 (non-taxable)	JPY 120,000 (non-taxable)	JPY 130,000 (non-taxable)
Student	JPY 40,000 (non-taxable)	JPY 50,000 (non-taxable)	JPY 75,000 (non-taxable)

Note

The on-site registration fee does not include admission to the welcome reception.

Registration and Payment

Registration and payment will be handled by Kinki Nippon Tourist Co., Ltd., the official conference agent. All payments must be made in Japanese yen (JPY) by credit card.

Please note that after the online registration deadline (September 7, 2026), online registration, modification of registration information, and online payment will no longer be available. Any changes or cancellations after the deadline must be requested by email and will be handled in accordance with the conference cancellation and refund policy. Cancellation fees and credit card service charges may apply.

For further details regarding registration procedures, payment, and cancellation policies, please visit the registration page on the conference website:

https://icscrm2026.org/registration/

Tutorial Program

A Tutorial Program will be held on Sunday, September 27. It is primarily intended for young researchers (PhD students and postdoctoral researchers) but is open to all participants. The tutorials will be delivered by invited experts and are designed to be accessible to attendees from diverse technical backgrounds. Separate registration and payment are required. Due to limited room capacity, registration may close before September 7 if the maximum number of participants is reached. If capacity permits, on-site registration will be available until the limit is reached. Participants may register through the conference website or at the on-site registration desk. The Tutorial Program registration fees are listed below.

	On-line (Until September 7 (JST))	On-site
Regular	JPY 15,000 (non-taxable)	JPY 15,000 (non-taxable)
Student	JPY 6,000 (non-taxable)	JPY 6,000 (non-taxable)

The registration fee includes participation in the tutorials, lunch, coffee breaks, and tutorial materials. Further details will be announced on the conference website.

Exhibition

An industrial exhibition will be held during ICSCRM 2026 at PACIFICO YOKOHAMA North. Companies involved in materials, devices, equipment, and services related to SiC and other wide-bandgap materials are invited to exhibit. The exhibition will run from September 28 to October 2, 2026, with booth setup on the afternoon of September 27 and dismantling on the afternoon of October 2. The Industrial Session will be held in conjunction with the exhibition. For further details, please visit the Technical Exhibition page on the conference website:

https://icscrm2026.org/exhibition/

or contact the exhibition section of the executive committee:

e-mail: exhibition@icscrm2026.org

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Sponsorship Opportunities

The International Conference on Silicon Carbide and Related Materials (ICSCRM) began in Washington D.C. in 1987. ICSCRM 2026 marks the 23rd edition of the series and the sixth time it will be held in Japan. The success of past ICSCRM conferences has been made possible by the generous financial support of companies engaged in this technical field. The organizers sincerely appreciate this continued support and kindly ask for your contribution to the success of ICSCRM 2026 as well.

For ICSCRM 2026, we are pleased to offer a variety of sponsorship packages and additional opportunities to showcase your company's commitment to the wide bandgap materials and power electronics community. These opportunities help highlight each sponsor's vital role in supporting the organization and success of ICSCRM 2026. We would be sincerely grateful for your kind cooperation and continued support.

For further details, please visit the Sponsorship Opportunities page on the conference:

https://icscrm2026.org/sponsorship/

Notes

Priority allocation of exhibition space and business meeting room will be granted to sponsors who submit both sponsorship and exhibition (or business meeting room) applications by the first-stage deadline and is valid only until designated booth quotas are filled (see the table below for details).
Payment must be completed within one month following your application.

Contact: ICSCRM 2026 Sponsor committee (sp-application@icscrm2026.org)

Sponsorship Packages

	Diamond **JPY 3,000,000** (non-taxable)	**Gold** **JPY 1,500,000** (non-taxable)	**Silver** **JPY 500,000** (non-taxable)
Advertisement in the program book	**1 page color**	**1 page color**	**1/2 page gray scale**
Logo exposure in the program book, on the conference website, and on onsite signage	**Large size**	**Middle size**	**Small size**
Priority allocation of exhibition space	**First priority in choosing exhibition space** If both sponsorship & exhibition applications are submitted by first-stage deadline Note: Valid only until designated booth quota is filled	**Second priority in choosing exhibition space** If both sponsorship & exhibition applications are submitted by first-stage deadline Note: Valid only until designated booth quota is filled	**Priority allocation to the 1st floor main hall** If both sponsorship & exhibition applications are submitted by the first-stage deadline deadline Note: Specific location selection is not available. Valid only until designated booth quota is filled
Priority allocation of business meeting room	**Priority in choosing business meeting room** If applications for both sponsorship and business meeting room are submitted by the first-stage deadline Note: Valid only until designated booth quota is filled	Not eligible	Not eligible
Application for supplementary sponsorship items and event support	Items: **I1 – I5** Events: **E1 – E5** (see details below)	Items: **I3 – I5** Events: **E3 – E5** (see details below)	Events: **E4 – E5** (see details below)

Other Sponsorship Opportunities

In addition to above sponsorship packages, less expensive sponsorship opportunities such as industrial session support. Confectionary for each coffee break, and banquet support are available. For further details, please visit the Web site above.

Supplementary sponsorship items

	Items	Benefit	Additional charge	Availability
I1	**Conference Bags**	Company logo printed on the bag tab distributed to each participant	**JPY 2,000,000** (non-taxable)	**Sold out**
I2	**Sake Tasting Cups**	Company logo printed on cups distributed to each Banquet attendees	**JPY 1,000,000** (non-taxable)	**1**
I3	**Name Badges and Lanyards**	Company logo printed on lanyards distributed to each participant	**JPY 500,000** (non-taxable)	**Sold out**
I4	**Pens**	Company logo printed on pens distributed to each participant	**JPY 500,000** (non-taxable)	**Sold out**
I5	**Notepads**	Company logo printed on notepads distributed to each participant	**JPY 500,000** (non-taxable)	**1**

Notice regarding supplementary sponsorship items:
Only sponsors who have applied for a sponsorship package are eligible to request additional sponsorship items. Selection is limited to one item per sponsor.

Supplementary event supports

	Events	Benefit	Additional charge	Availability
E1	**Banquet**	Company logo displayed at the banquet venue + one free conference admission, including banquet participation	**JPY 2,000,000** (non-taxable)	**No limitation**
E2	**Welcome Reception**	Company logo displayed at the welcome reception venue + one free conference admission (banquet not included)	**JPY 1,500,000** (non-taxable)	**No limitation**
E3	**Industrial Session**	Company logo displayed at the industrial session venue + one free conference admission (banquet not included)	**JPY 1,000,000** (non-taxable)	**No limitation**
E4	**Coffee Break**	Company logo displayed in each coffee break area + one free conference admission (banquet not included)	**JPY 500,000** (non-taxable)	**No limitation**
E5	**Lunch**	Company logo displayed at each conference lunch venue + one free conference admission (banquet not included)	**JPY 500,000** (non-taxable)	**No limitation**

Notice regarding supplementary event supports:
Only sponsors who have applied for a sponsorship package are eligible to request additional event supports. There is no limit to the number of units that may be purchased.

Social Events

● Welcome Reception

A welcome reception will be held on Sunday evening, September 27, 2026, at PACIFICO YOKOHAMA North (Multi-Purpose Hall). This event provides an excellent opportunity for participants to obtain conference materials and to network with fellow attendees in a relaxed setting.

● Banquet

A conference banquet will be held on Thursday evening, October 1, 2026, at the Osanbashi Yokohama International Terminal. Known for its more than 130-year history as the "gateway to the sea" since the opening of the Port of Yokohama, Osanbashi is a symbolic landmark of the city. Participants are invited to enjoy the scenic night view and unique atmosphere of Yokohama's waterfront together.

General Information

● Accommodations

Participants are requested to arrange their own hotel accommodation during the conference. Please note that the conference does not provide a hotel booking service, and no special accommodation rates are offered for conference attendees.

For hotel selection, the nearest districts to PACIFICO YOKOHAMA North are Minato Mirai 21 and Sakuragi-cho. Other convenient areas, such as Yokohama Station and Chinatown / Kannai / Yamashita Park, are also located close to the Minato Mirai 21 district and offer a wide range of accommodation options.

Please refer to the "WHERE TO STAY" link for further information on recommended districts and hotels.

https://www.yokohamajapan.com/where-to-stay/

● Passport and Visa

All overseas participants entering Japan must hold a valid passport. Participants who require a visa are responsible for obtaining one from the nearest Japanese embassy or consulate prior to travel. For ICSCRM 2026, visa-related assistance documents may be provided to eligible participants. If you require visa support or have any questions regarding the application process, please contact the conference secretariat:

secretariat@icscrm2026.org

For official visa requirements and procedures, please consult your nearest Japanese diplomatic mission.

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	Mari Yamamoto	Lasertec Corporation, Japan
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	Makoto Takeda	Resonac Corporation, Japan
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	Kazuoki Matsugatani	Denso Corporation, Japan
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	Victor Veliadis	PowerAmerica, USA
	Hiroshi Yano	University of Tsukuba, Japan

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	Hiroyuki Matsunami	Kyoto University, Japan
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